


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	POWER AND DISCRETES/25/16034	
1.3 Title of PCI	Sealing process change for Diodes and Power MOSFETs in SMD.5 and TO257AA packages.	
1.4 Product Category	All ESCC Diodes and Power MOSFETs assembled in SMD.5 and TO-257AA packages.	
1.5 Issue date	2025-12-28	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Stephane CHAMARD,Rosario RUGGERI
2.1.2 Marketing Manager	Philippe LEGER,Giuseppe CAMONITA
2.1.3 Quality Manager	Emmanuelle GUERINEL

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Change in process technique for molding/encapsulation	ST Microelectronics Rennes - France

4. Description of change

	Old	New
4.1 Description	Parallel seam welding	Furnace sealing
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No	

5. Reason / motivation for change

5.1 Motivation	This change increases production capacity and ensures service continuity.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	New Finished Good print on labels. Date code, written on the parts and on the Certificate of Conformance, fully identifies the parts' manufacturing flow.
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7. Timing / schedule

7.1 Date of qualification results	2025-12-31
7.2 Intended start of delivery	2026-02-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16034 Public product.pdf
16034 Oven sealing on diodes and pwmos SMD_5 TO257AA rev1.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STPS60A150CS1	

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